

Claims:

1 1. A printed circuit board mounted with a wireless
2 communication board, comprising:
3 multilayer structural conductive layers including a first
4 conductive plane connected to power supply potential and a
5 second conductive plane connected to ground potential;
6 wherein,
7 said first and second conductive planes are formed such
8 that: one conductive plane interposes between the other
9 conductive plane and a surface of said printed circuit board on a
10 side where said wireless communication board is mounted, and an
11 electric field generated by a potential difference between said
12 power supply potential and said ground potential is concentrated
13 on a side of said the other conductive plane rather than a side of
14 said one conductive plane.

1 2. The printed circuit board according to Claim 1, wherein:
2 said printed circuit board comprises a conductive belt that
3 is formed in a conductive layer in which said the other conductive
4 plane lies, and located adjacent to said the other conductive plane
5 with slits interposing between said conductive belt and said the
6 other conductive plane; and
7 said conductive belt is electrically connected to said one
8 conductive plane.

1 3. The printed circuit board according to Claim 1, wherein:

2 said printed circuit board further comprises a U-shaped
3 conductive member that encloses a part of said printed circuit
4 board to cover the surface of said printed circuit board in an area
5 over which said wireless communication board is mounted, and
6 said conductive member is electrically connected to said
7 one conductive layer.

1 4. The printed circuit board according to Claim 1, wherein:
2 said the other conductive plane is formed in a smaller size
3 than said one conductive plane, and located within an area of said
4 one conductive plane.

1 5. The printed circuit board according to Claim 1, wherein:
2 said printed circuit board comprises:
3 a conductive belt that is formed in a conductive layer in
4 which said the other conductive plane lies, and located adjacently
5 to said the other conductive plane with slits interposing between
6 said conductive belt and said the other conductive plane; and
7 a third conductive plane formed in a conductive layer that
8 is located on an opposite side to said one conductive plane with
9 respect to said the other conductive plane;
10 wherein:
11 said conductive belt and said third conductive plane are
12 electrically connected to said one conductive plane.

1 6. A wireless communication apparatus comprising:
2 a printed circuit board according to Claim 1; and
3 a chassis that houses said printed circuit board.

1 7. The wireless communication apparatus according to Claim
2 6, further comprising:
3 a radio wave absorption member that is located inside said
4 chassis, and absorbs an electric field generated by a potential
5 difference between said power supply potential and said ground
6 potential.